

Simulation, Fabrication, and Measurement of Infrared Frequency Selective Surfaces

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SANDIA

SEI

5.0kV

X8,000

1 μ m

WD 16.0mm

Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company, for the United States Department of Energy's National Nuclear Security Administration under Contract DE-AC04-94AL85000.

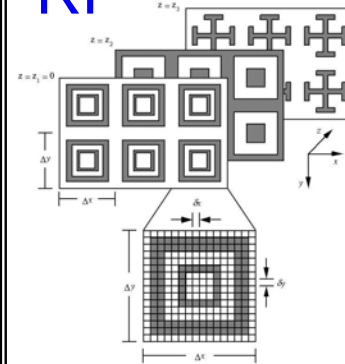
Introduction

Used in radomes and other RF applications, the surface allows near 100% transmission over a broad angular and spectral range.

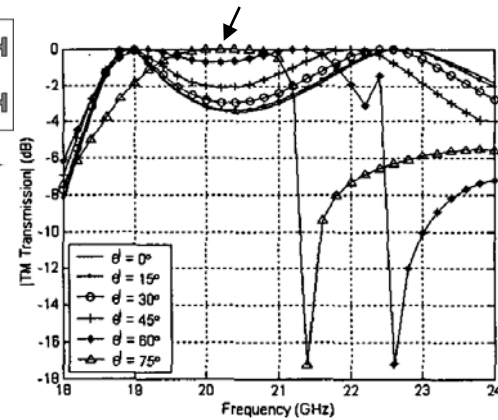
We will show the fabrication of a frequency selective surface (FSS) that allows high optical transmissions over relatively broad frequencies or angular bands.

Allows a conductive surface with high transmission.

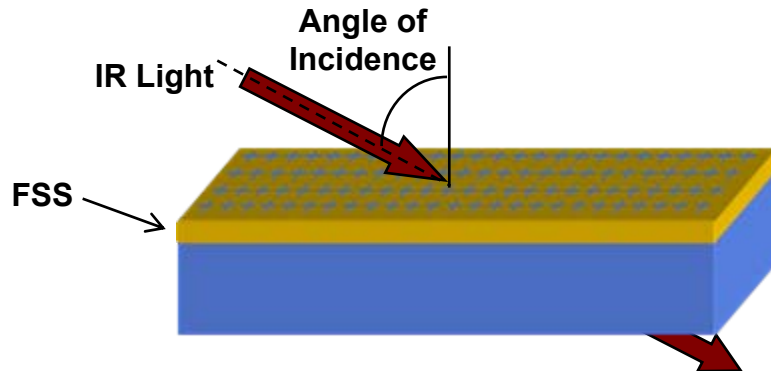
RF



100% transmission at 75°

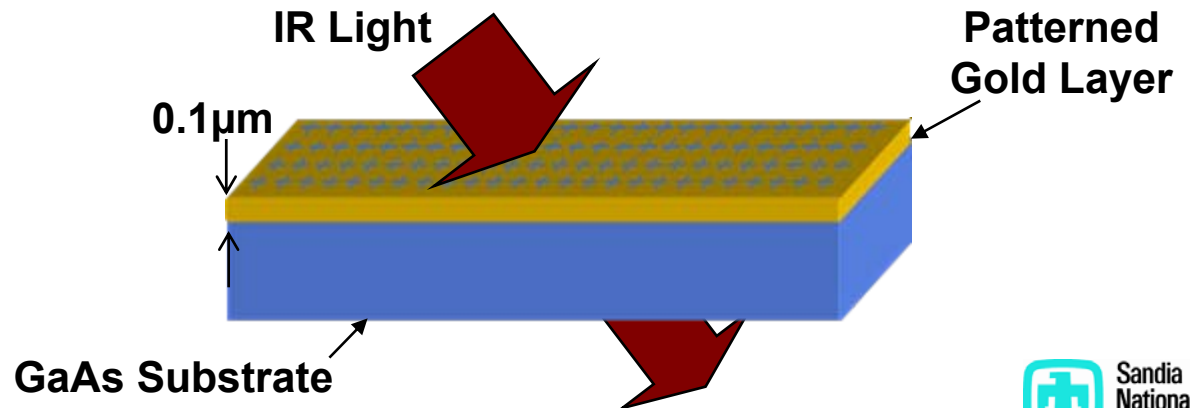


IR



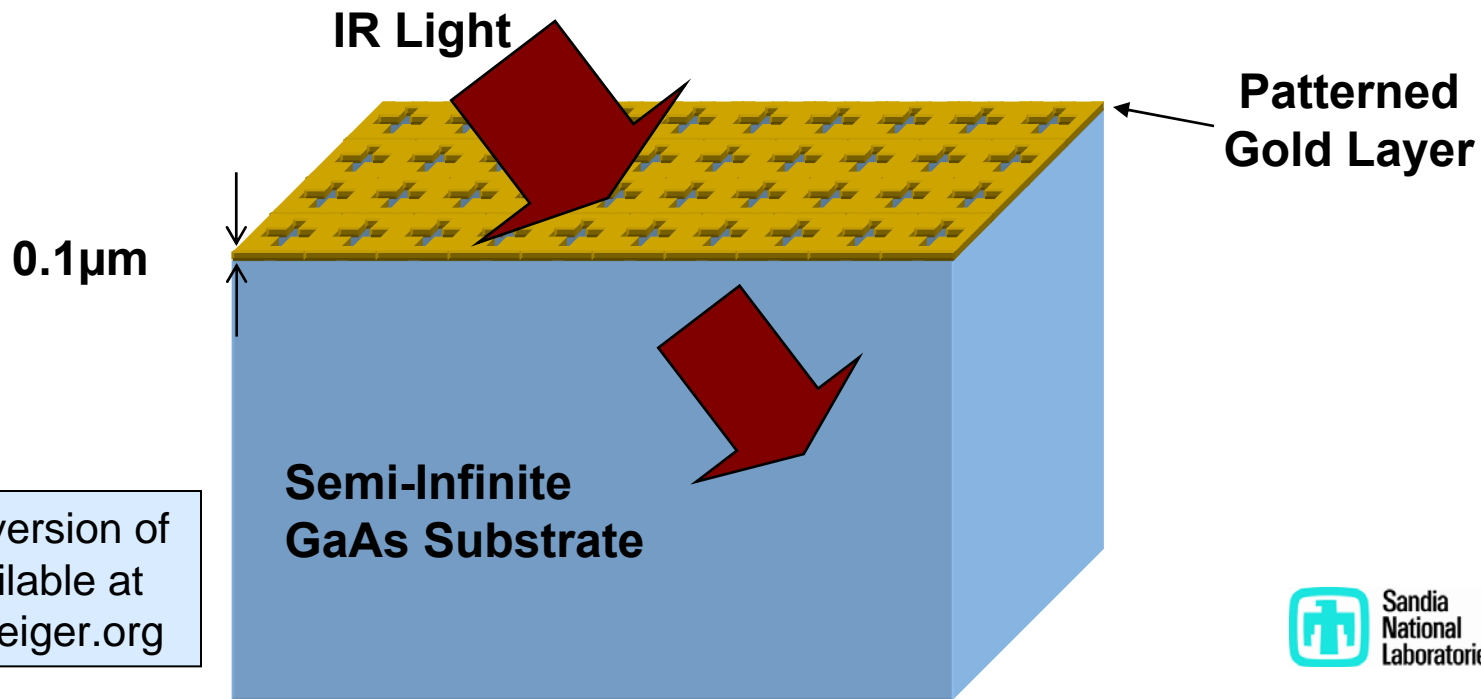
Introduction

- We are investigating **single metal layer** and **metal layer + dielectric cover layer** structures that show significant transmission over a large angular range.
- Unlike most free-standing RF structures we are looking at creating FSS's on windows, so must consider the substrate in the design.



Modeling & Design with EIGER™

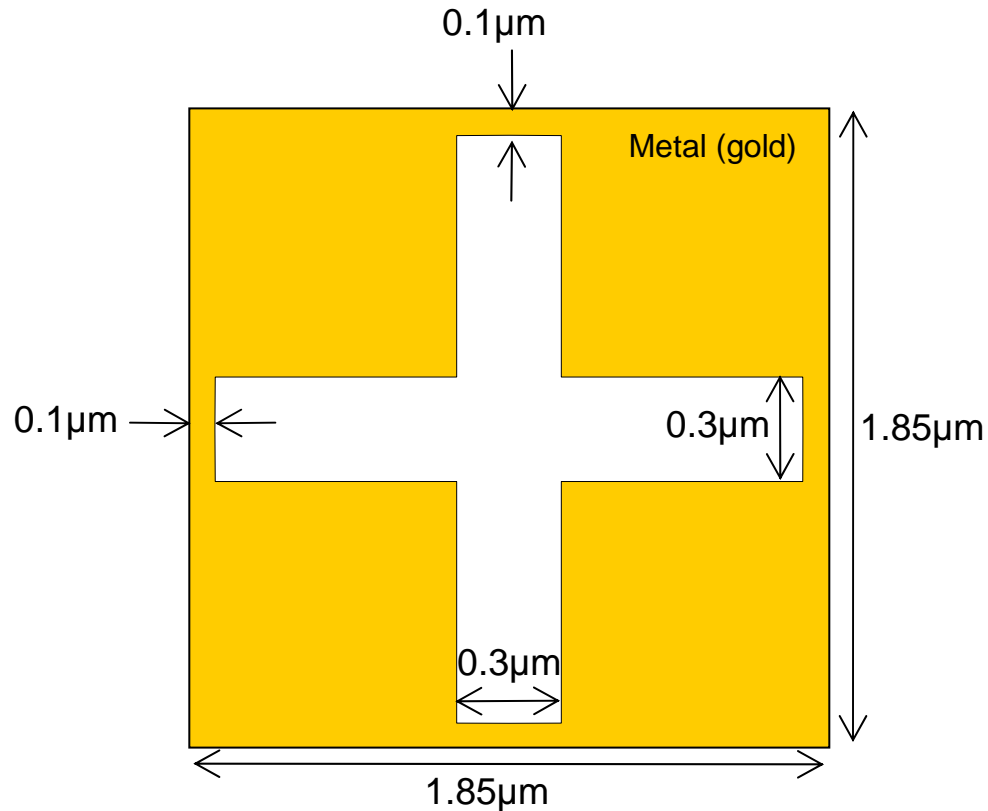
- Design and modeling were performed using Electromagnetic Interactions GenERalized (EIGER™), the frequency-domain integral equation code maintained by Sandia and the University of Houston.
- The EIGER™ model incorporates **finite conductivity** and **dispersion** of bulk gold.



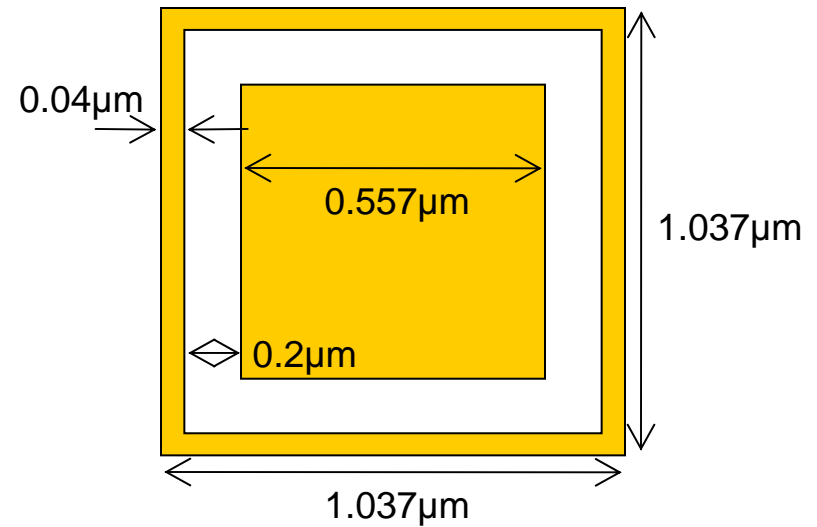
An open-source version of
EIGER™ is available at
<http://www.code-eiger.org>

Modeling & Design: EIGER™ Unit Cells

Design 1



Design 2

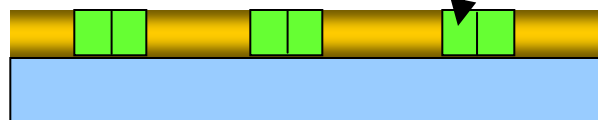
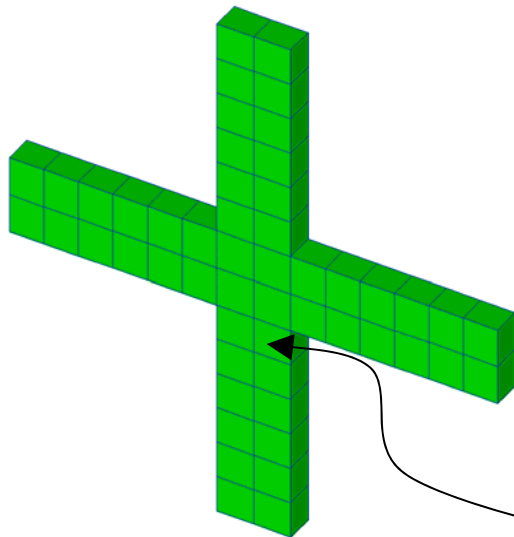


Periodic boundary conditions used in the lateral dimensions.

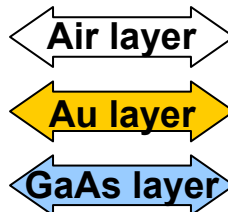
Modeling & Design: EIGER™ meshing options

Aperture Mesh

(used with a layered-media Green's Function)



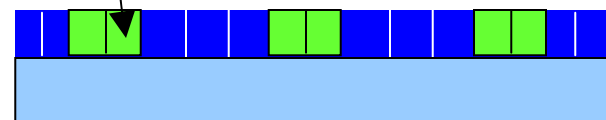
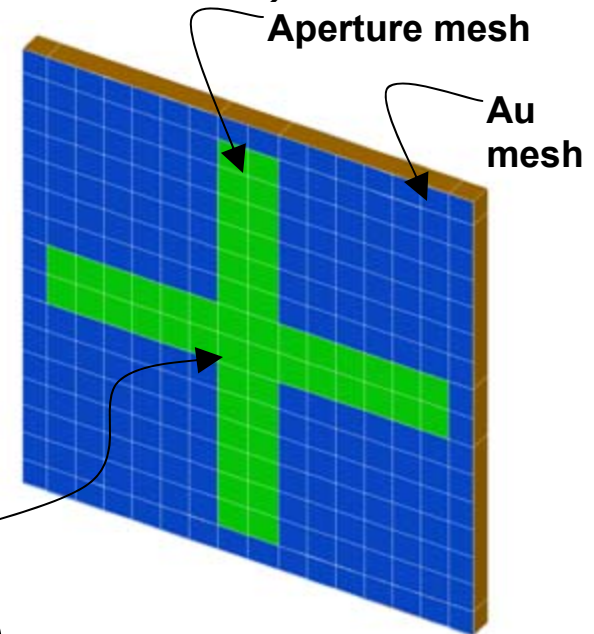
Aperture mesh



Fewer mesh points in this configuration leads to faster execution times.

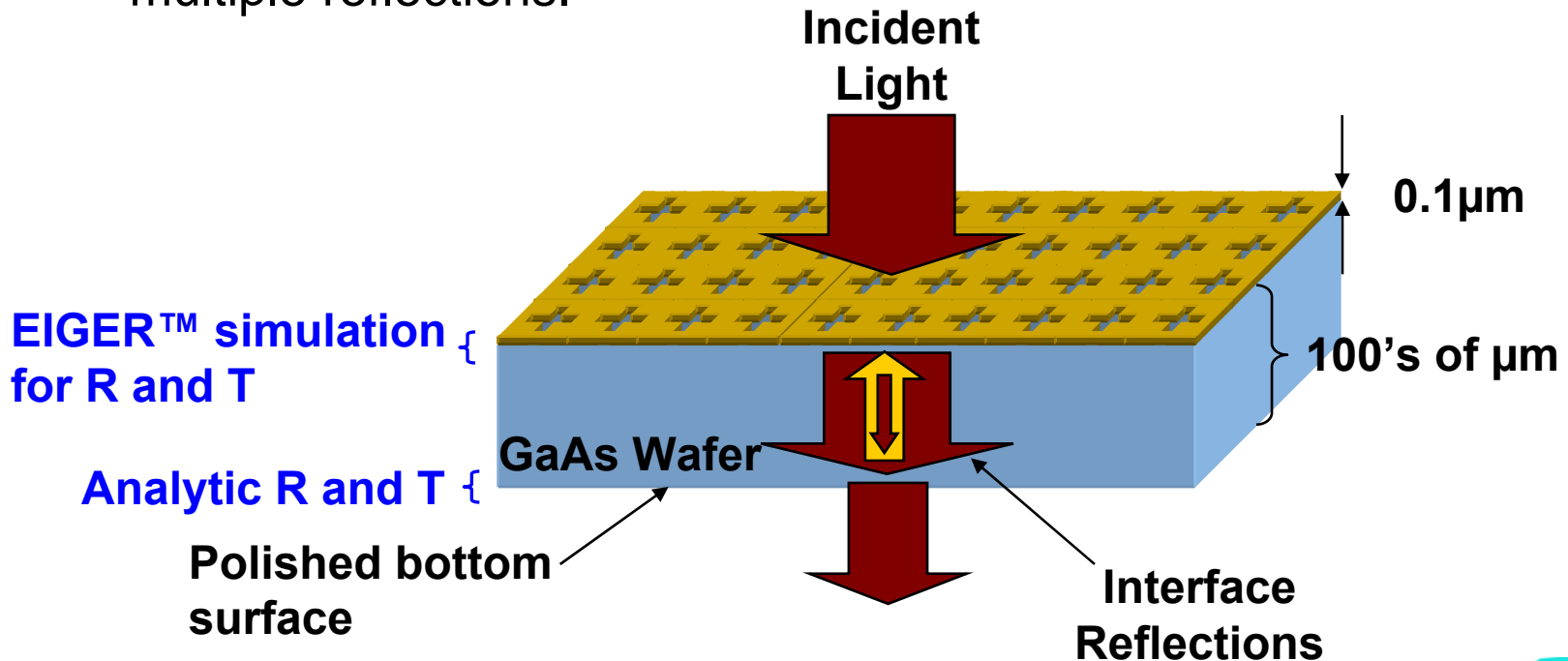
Explicit Unit-Cell Mesh

(used with a homogeneous Green's function)



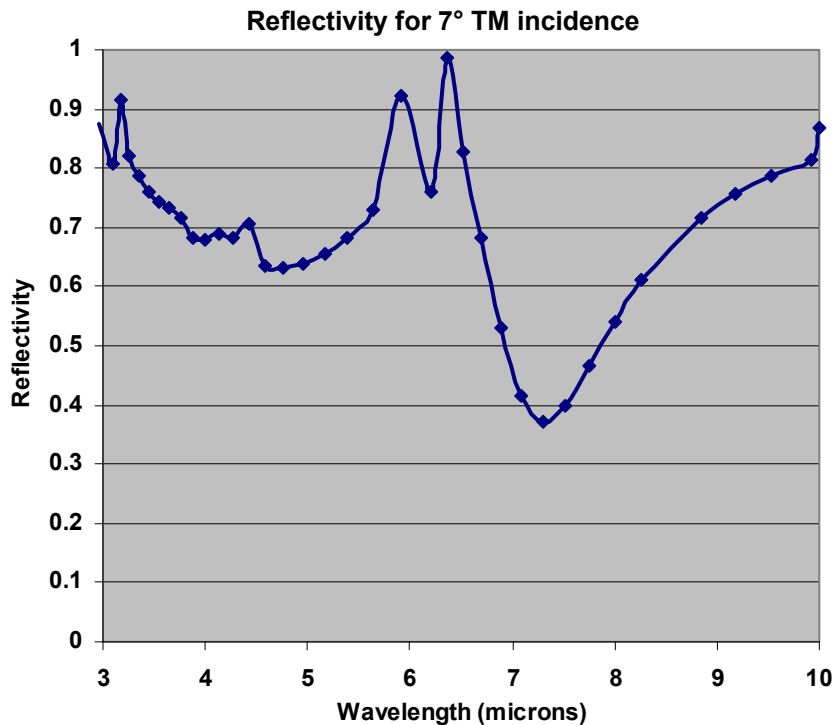
Modeling & Design: Accounting for back surface reflections

- The actual fabricated part has a back surface that leads to more reflections.
- Reflections from the polished back surface of the wafer are easily calculated using Fresnel's equations and accounting for multiple reflections.

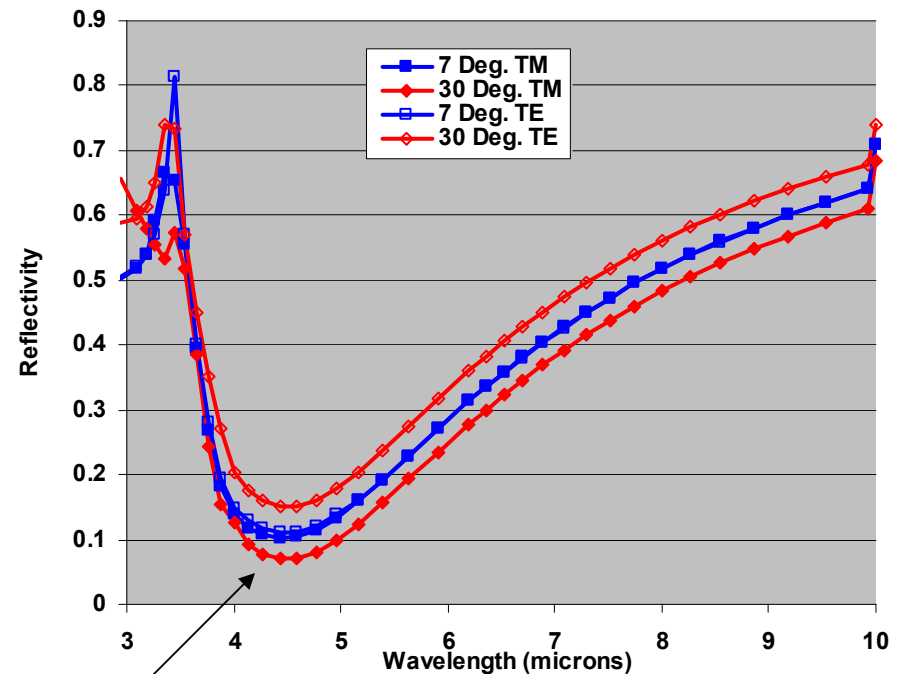


Calculated Reflectivities

Simulation of Design 1

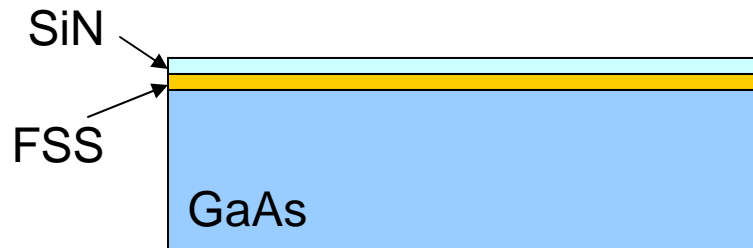


Simulation of Design 2

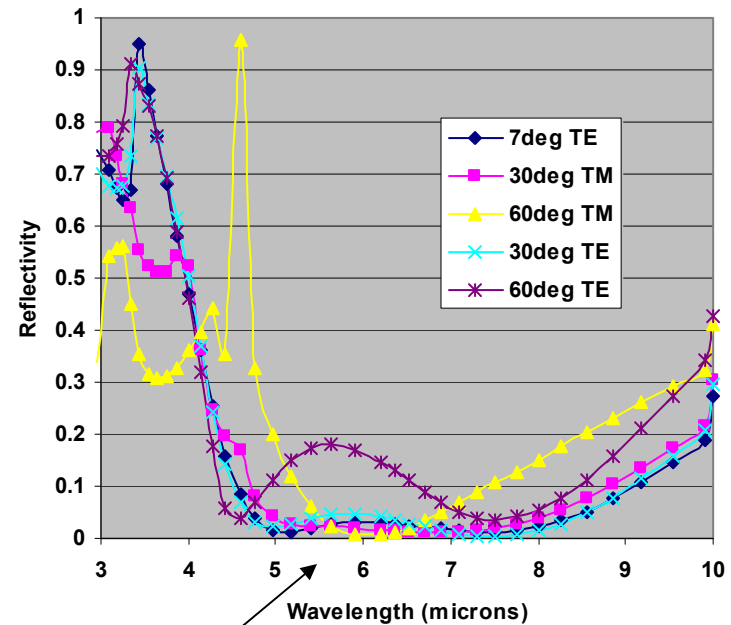


Square-loop device has significantly better performance.

Reflectivity of Square-Loop Design with Added Matching Layer



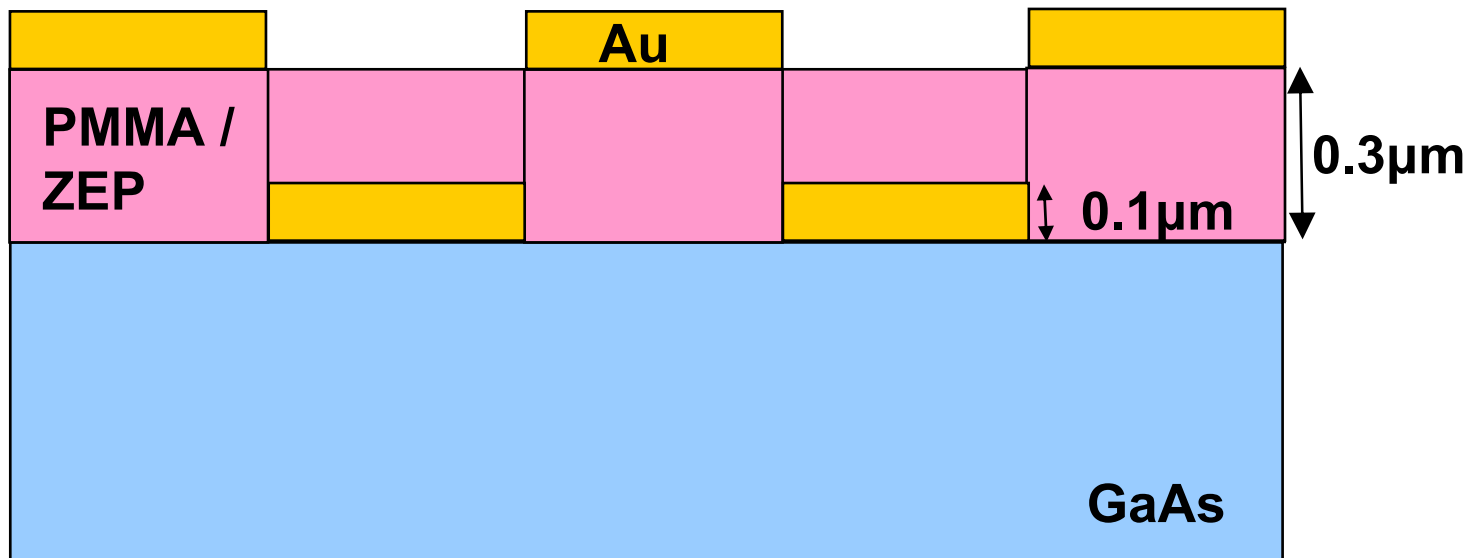
Simulation of Design 2
with cover layer of 0.9 μm
of SiN



Very low reflectivity for both polarizations over a broad angular range.

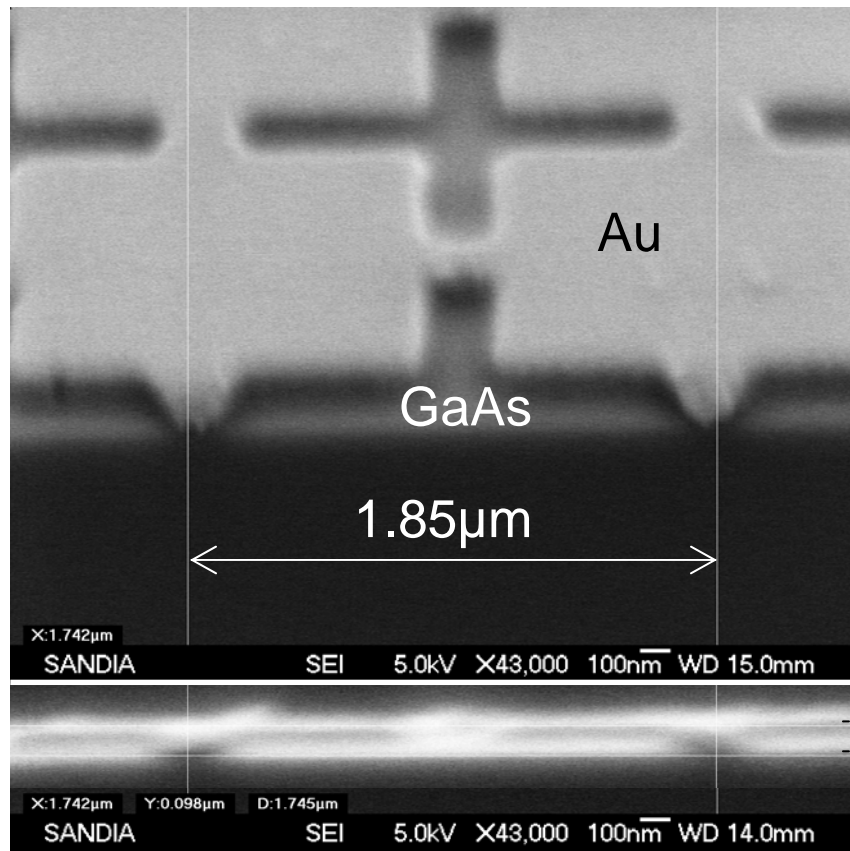
Fabrication Steps

- Spin PMMA (Design 1) or ZEP520A (Design 2) on top of GaAs.
- E-beam write the pattern.
- Evaporate $0.1\mu\text{m}$ of gold on top a GaAs substrate with/without a Ti adhesive layer.
- Perform liftoff to obtain the desired pattern.



Fabrication

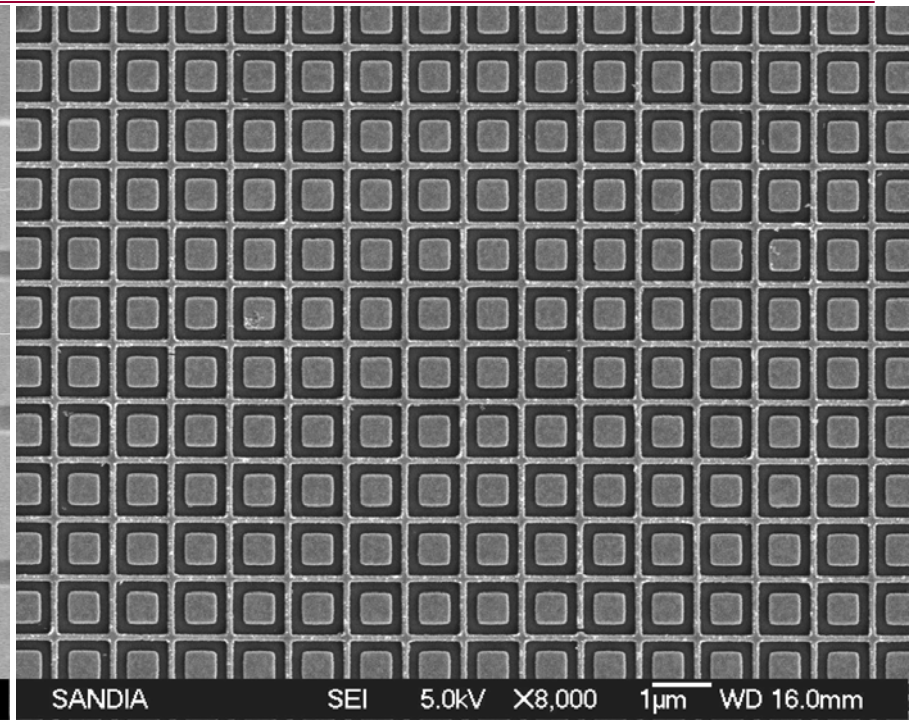
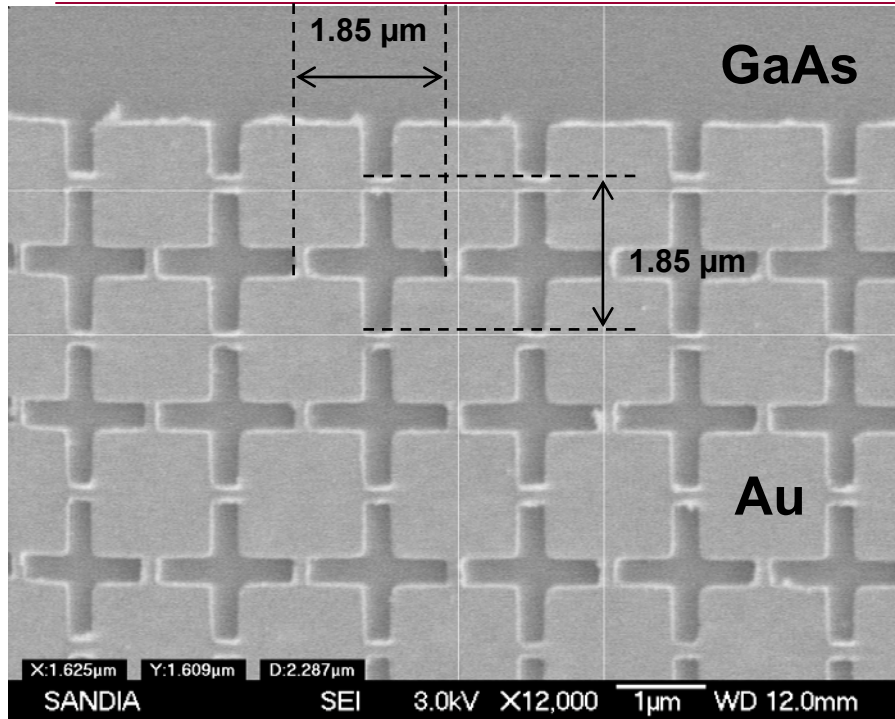
Isometric View



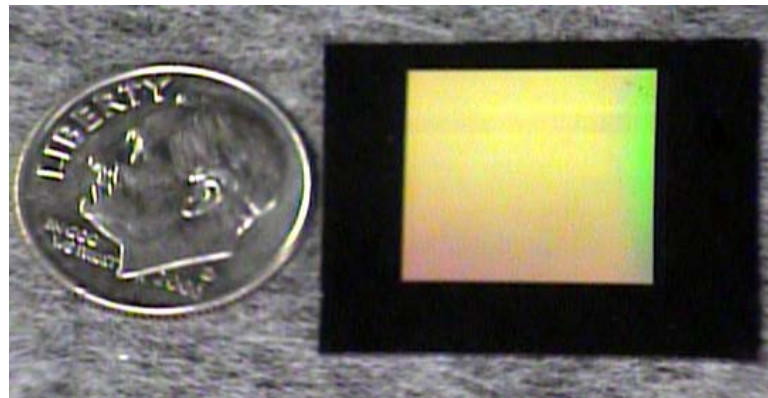
Side View

The metal layer is optically thick across the waveband of interest.

Fabricated Designs

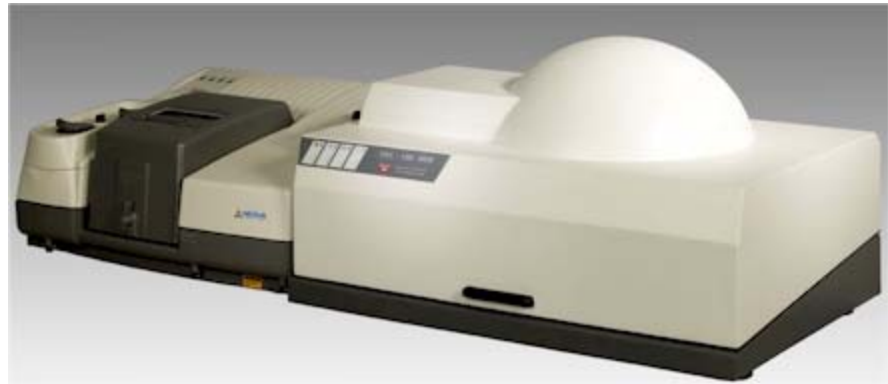
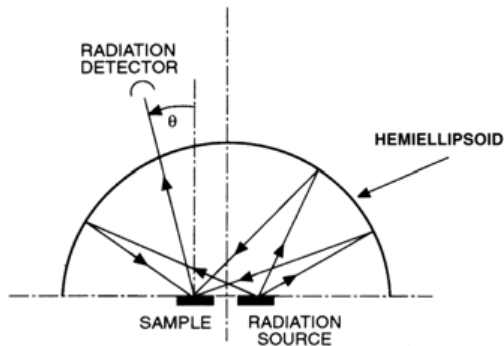


Overall device size is dictated by the requirements for measuring far off-axis R and T.



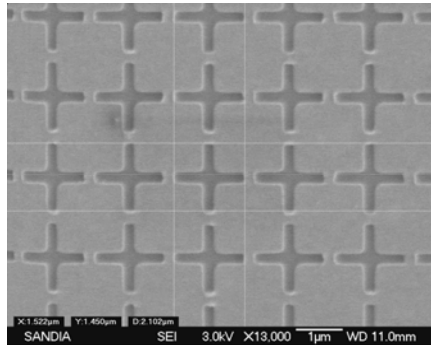
Measurement System

- **Fabrication:** E-beam, using both positive and negative resists and variable doses depending on the pattern.
- **Test and measurement:** We use a hemispherical directional reflectometer (SOC-100) that can give us broadband and broad angle reflection and transmission measurements.

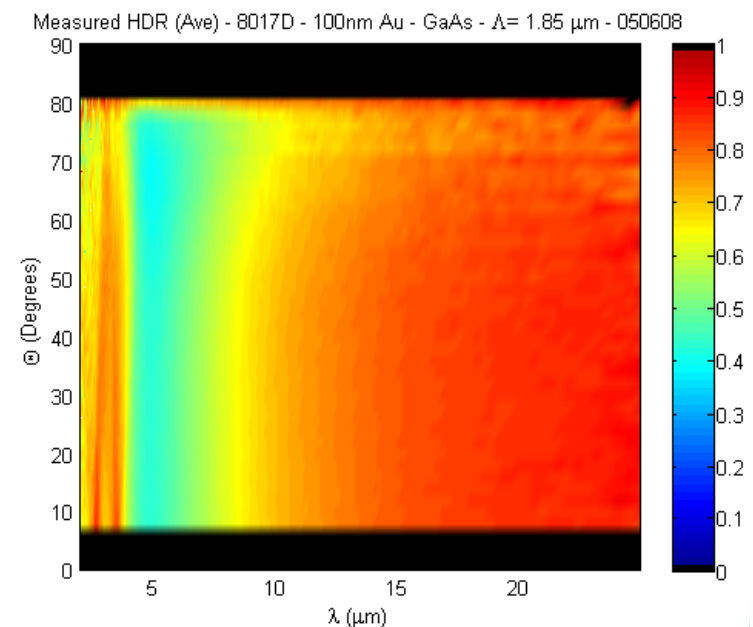
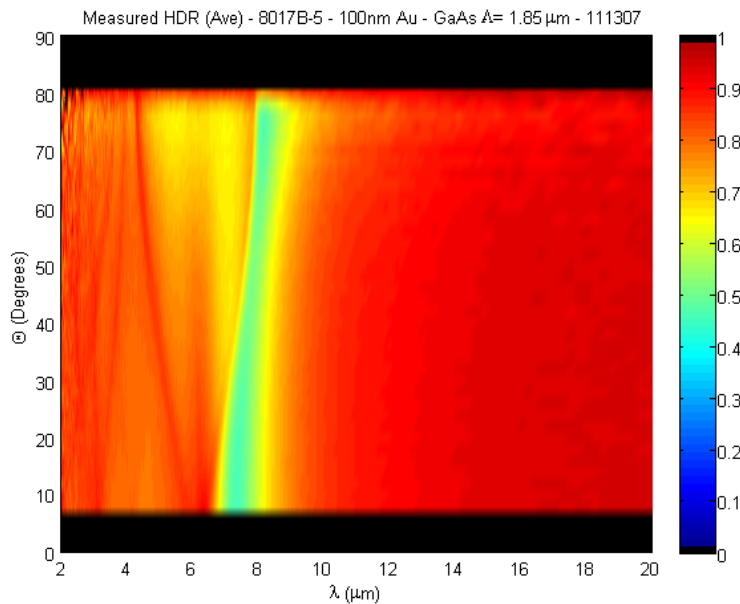
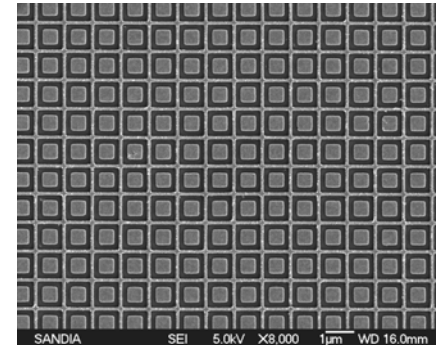


Comparison of the Results from the Two Designs

Design 1

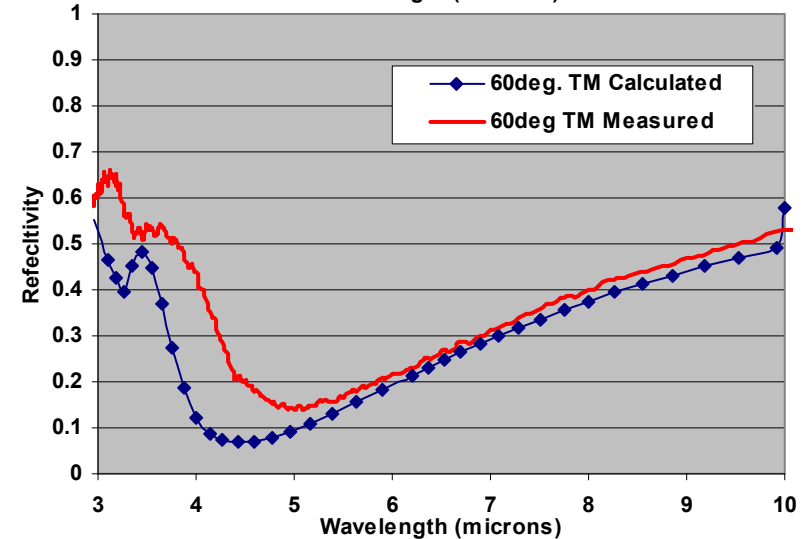
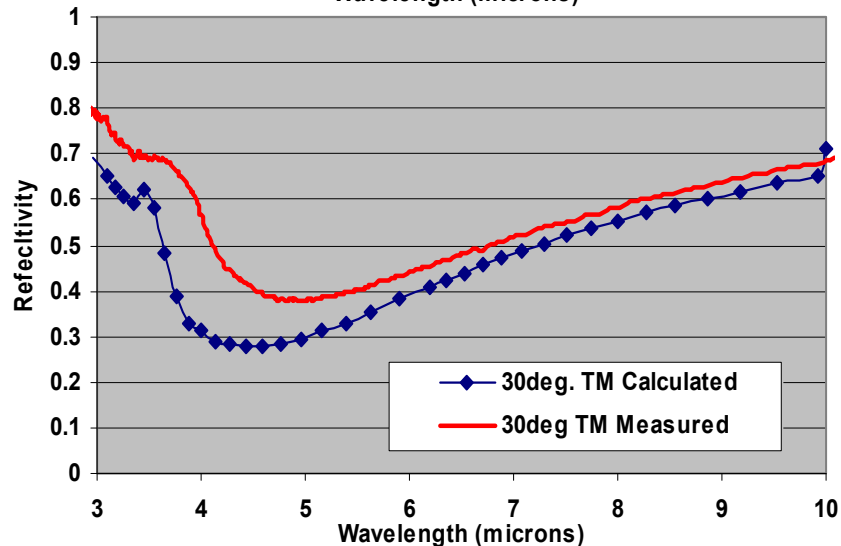
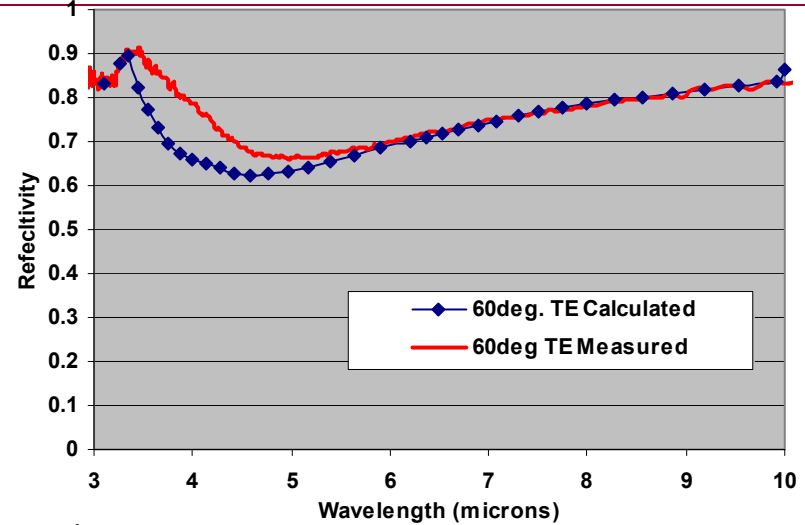
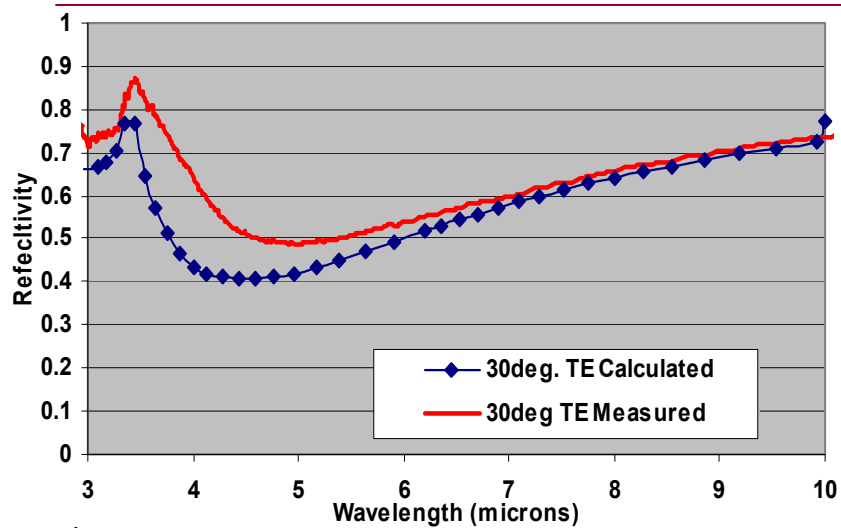
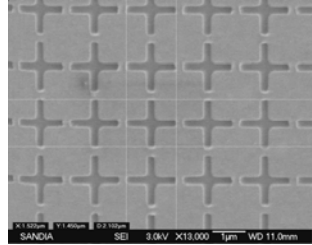


Design 2



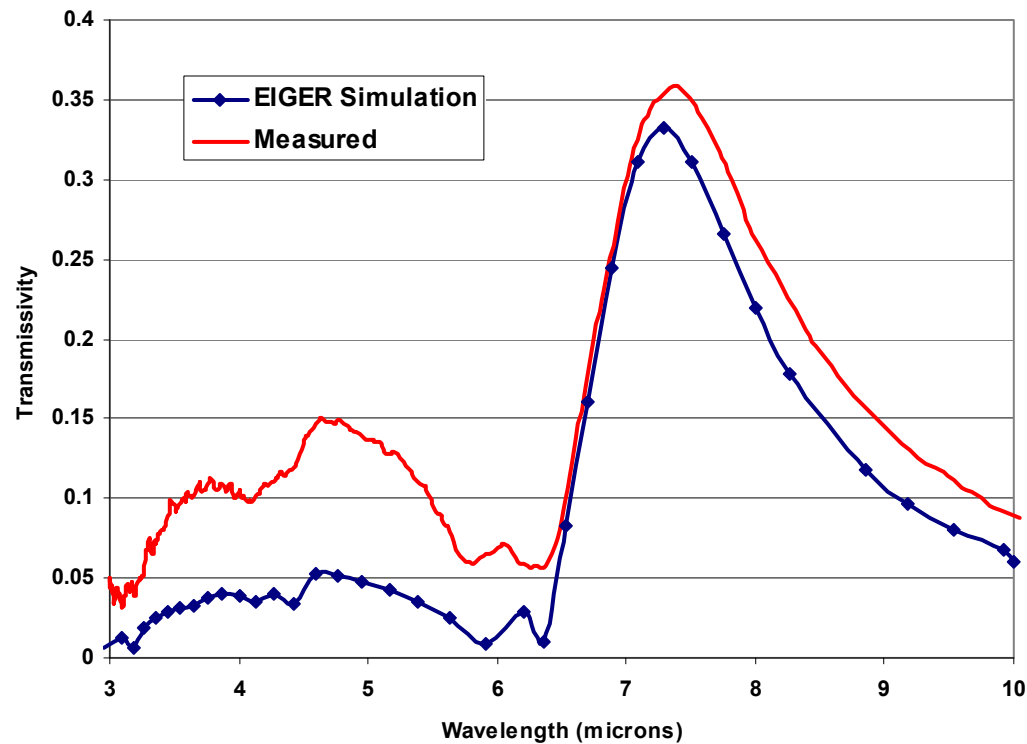
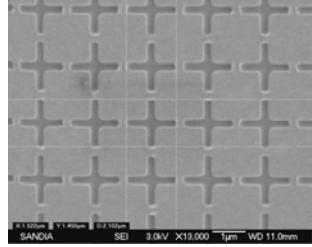
Measurements include reflections from back surface of wafer.

Good Agreement between Reflection Measurement and Simulation



Design 2 without cover layer and accounting for back surface.

Transmission Measurement Comparison to Model



We are continuing to investigate the reason for the differences at the higher frequencies.



Summary

- **Modeled and designed FSSs using EIGER™ including finite conductivity and dispersion of the metal.**
- **Fabricated and tested two designs.**
- **Demonstrated broad angular range transmission through a largely metallic surface in the MWIR.**



Acknowledgements

William A. Johnson	Code Developer
Lorena I. Basilio	Simulations
Alvaro A. Cruz-Cabrera	Measurements
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Shanalyn A. Kemme	Fabrication Coordinator
Sally Samora	Device Fabrication

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